

Most Frequently Occurring Classifications of Patents Returned
From A Search of 10/600,568 on December 23, 2003

Combined Classifications

6 257/E21.576
5 257/723
5 257/763
4 257/700
4 257/E21.582
4 257/E23.173
4 257/E23.193
3 257/686
3 257/704
3 257/751
3 257/758
3 257/765
3 257/E21.648
3 361/760
3 438/622
2 174/52.4
2 257/198
2 257/306
2 257/668
2 257/685
2 257/697
2 257/712
2 257/713
2 257/717
2 257/722
2 257/724
2 257/762
2 257/764
2 257/766
2 257/777
2 257/E21.278
2 257/E21.387
2 257/E21.507
2 257/E21.579
2 257/E21.645
2 257/E21.705
2 257/E23.094
2 257/E23.167
2 257/E23.19
2 257/E25.013
2 257/E27.012
2 257/E29.189

2 361/749
2 361/767
2 361/783
2 361/807
2 361/810
2 361/816
2 361/818
2 385/92
2 438/109
2 438/613
2 438/638
2 438/687
2 438/724
2 438/745

- 5 257/723 (0 OR, 5 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/688 .With large area flexible electrodes in press
contact with opposite sides of active semiconductor chip
and surrounded by an insulating element, e.g., ring
257/723 .For plural devices
- 5 257/763 (0 OR, 5 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/741 .Of specified material other than unalloyed
aluminum
257/750 ..Layered
257/763 ...At least one layer of molybdenum, titanium,
or tungsten
- 4 257/700 (0 OR, 4 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/688 .With large area flexible electrodes in press
contact with opposite sides of active semiconductor chip
and surrounded by an insulating element, e.g., ring
257/690 .With contact or lead
257/700 ..Multiple contact layers separated from each
other by insulator means and forming part of a package or
housing (e.g., plural ceramic layer package)
- 3 257/686 (2 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/678 HOUSING OR PACKAGE
257/685 .Multiple housings
257/686 ..Stacked arrangement
- 3 257/704 (1 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/688 .With large area flexible electrodes in press
contact with opposite sides of active semiconductor chip
and surrounded by an insulating element, e.g., ring
257/701 .Insulating material
257/704 ..Cap or lid
- 3 257/751 (2 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/741 .Of specified material other than unalloyed
aluminum
257/750 ..Layered

257/751 ...At least one layer forms a diffusion barrier

3 257/758 (1 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD

257/741 .Of specified material other than unalloyed
aluminum

257/750 ..Layered

257/758 ...Multiple metal levels on semiconductor,
separated by insulating layer (e.g., multiple level
metallization for integrated circuit)

3 257/765 (0 OR, 3 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD

257/741 .Of specified material other than unalloyed
aluminum

257/750 ..Layered

257/765 ...At least one layer of an alloy containing
aluminum

3 438/622 (1 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING:
PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive
material

438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)

438/622 ...Multiple metal levels, separated by
insulating layer (i.e., multiple level metallization)

PLUS Search Results for S/N 10/600,568, Searched December 23, 2003 (TOP 50)

6611060	6140208	5466634	4943470	5670801
5412748	6162740	5517057	4965660	5683940
5559918	6166425	5654567	5188280	5700720
5387815	6251786	5898221	5333505	5818699
5426319	6294422	5705847	5399527	5916733
5525548	6300242	4251852	5506451	5949654
5691222	6333248	4322279	5506755	5949097
5872060	6333547	4490706	5519254	5981000
6025623	6376353	4764804	5532906	6037247
6124553	6376386	4769690	5656856	6096630